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(IEC 63563-10:2025)**

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(IEC 63563-10:2025)

Qi Spezifikation Version 2.0 - Teil 10: Mpp System
Spezifikation
(IEC 63563-10:2025)

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INTERNATIONAL STANDARD

**Qi Specification version 2.0 –
Part 10: MPP System Specification**

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Part 10: MPP System Specification

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Qi Specification

MPP System Specification

Version 2.0

April 2023

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1 General Description

1.1 Introduction

1.1.1 Scope

This specification defines MPP (Magnetic Power Profile), an extension to Qi v1.3 BPP (Baseline Power Profile). Manufacturers can use this specification to implement PTx and/or PRx that are interoperable.

1.1.2 Document organization

The MPP (Magnetic Power Profile) Specification is organized as these documents:

1. MPP System Specification (this document)
2. MPP Communications Protocol

koniec náhľadu – text ďalej pokračuje v platenej verzii STN